



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Jun AMAKO et al.

Application No.: 09/801,699

Filed: March 9, 2001

Docket No.: 108850

For: PACKAGE SEALING METHOD, MANUFACTURING METHOD OF ELECTRONIC
DEVICE MODULES, SEALING APPARATUS, AND PACKAGED PRODUCT

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

Page 10, line 1 to line 27, delete current paragraph and insert therefor:

Fig. 2 is a view to explain a manufacturing apparatus of a crystal oscillator module according to a first embodiment of the present invention. In this first embodiment, the bonding member 16 is interposed between the case 10 housing a crystal oscillator and a lid 14 (see Fig. 3), and the latter has a bonding member 16 with a low melting point attached to the periphery on its inner surface. Then, these components are set between a stationary side 30 and a mobile side (made of material that transmits the laser beam) 32 of a pressure apparatus in Fig. 2. These stationary side 30 and mobile side 32 are clamped with a clamp screw 34 so that the case 10 and the lid 14 are pressed and fixed. After the lid 14 and the case 10 are

RECEIVED
AUG - 6 2001
TC 3700 MAIL ROOM

7/26/01
K. Cobb
8/8/01

3700
0360
3721

231